Combine Type Connector (for SD Memory Card, MultiMediaCard™, Memory Stick™)

SCDB Series



Push-push type featuring contact protection function with less impact to media cards.

For SD Memory Card

For microSD™ Card

For SIM Card 8pins

For Memory Stick Micro™

Combine Type

For W-SIM



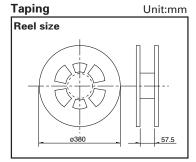
Typical Specifications

Items			Specifications			
	Applicable media		SD Memory Card, MultiMediaCard™, Memory Stick™			
Structure	Mounting type		Surface mounting type			
Structure	Mounting style		Standard mount/ Reverse mount			
	Media ejection structure		Push-push type			
	Operating temperature range		−20°C to +60°C			
	Voltage proof		100V AC 1minute			
Performance	Insulation resistance (Initial)		1,000MΩ min.			
renormance	Contact resistance (Initial)	Connector contacts	100mΩ max.			
		Detection switch	500mΩ max.			
	Insertion and removal cycle		10,000cycles (SD Memory Card) 12,000cycles (Memory Stick™)			

Product Line

Media ejection structure	Mounting system	Feature	Stand- off(mm)	Packing system	Product No.	Drawing No.	
Push-push type	Standard mount	With boss	0	Taping	SCDB3A0202	1	
i usii-pusii type	Reverse mount	WILLI DOSS			SCDB4A0101	2	

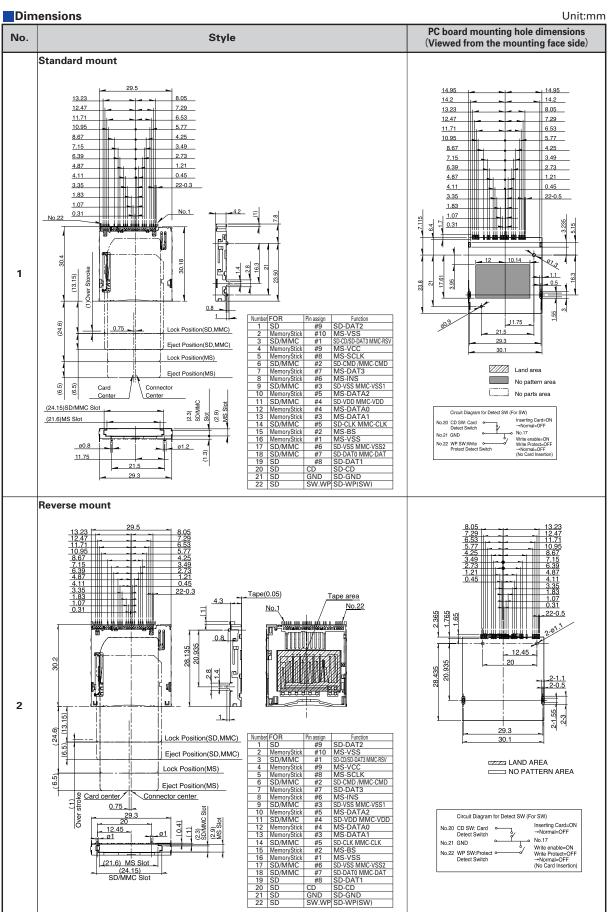
Packing Specifications



Numb	er of packages	Tape width	Export package measurements	
1 reel	1 case /Japan	1 case /export packing	(mm)	(mm)
300	600	1,200	56	403×403×297

Note

Please place purchase orders per minimum order unit N (integer).



ALPS

SD Memory

microSD™

SIM Card

Card

For

Card

For

8pins

Memory

Stick Micro™

Combine Type

546

For W-SIM

List of Varieties

A	pplicable media	Product No.	Photo	Media ejection structure	Mounting style	Features	Stand-off (mm)	Auto motive use	Page
SIM Card 8pins Memory Stick Micro™		SCGC1B0101				With switch		0	541
		SCGC1B0301			Standard mount	With Automatic Locking Cam			341
		SCNA1A0300				Without boss			543
Combine Type	SD Memory Card Multi-Media Card™ Memory Stick™	SCDB3A0202		Push-push type			0		545
		SCDB4A0101			Reverse mount	- With boss			343
	SD Memory Card Multi-Media Card™ Multi- Media Card Plus™ Memory Stick™ xD-Picture Card™	SCDG1A0101			Standard mount				547
		SCDG2A0101			Reverse mount				
	SD Memory Card Multi-Media Card™ Memory Stick™ xD-Picture Card™	SCDG4B0100				Thin with a Thickness of 4.2mm			549
	microSD™ Card SIM Card 8pins	SCHG1B0100		Push-push type Manual insertion/ removal		microSD™ Card right insertion type			551
		SCZA1A0100			Standard	Without boss L type			
		SCZA1A0200		Push-push		With boss L type			
		SCZA1A0300 SCZA1A0400		type	mount	Without boss 0.6mm type With boss 0.6mm type			
		SCZA1A0500 SCZA1A0600				Without boss 1.2mm type With boss 1.2mm type			
	W-SIM	SCZATA0600		Manual - insertion/ removal		With boss L type			553
		SCZA2A0200				Without boss 0.6mm type			

For SD Memory Card

For microSD™ Card

For SIM Card 8pins

For Memory Stick Micro™

Combine Type

For W-SIM

Note

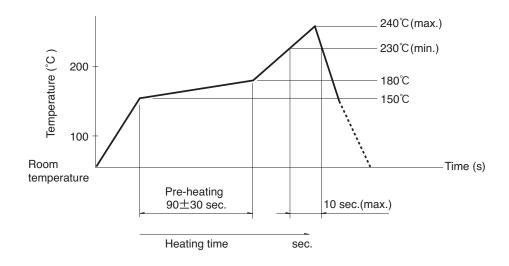
Omarks in "Available for automotive use" indicate that some of the series products can work at the operating temperature range from -40°C to +85°C.

Please place purchase orders per minimum order unit N (integer).

Soldering Conditions

Example of Reflow Soldering Condition (Reference)

- 1. Heating method: Double heating method with infrared heater.
- 2. Temperature measurement: Thermocouple 0.1 to 0.2 φ CA (K) or CC (T) at soldering portion.
- 3. Temperature profile



For SD Memory Card

For microSD™ Card

For SIM Card
8pins

For Memory Stick Micro™

Combine Type

For W-SIM

Please refer to each product's specification sheet to confirm temperature profile.

Cautions for using this product

- 1. Connector hamdling precautions
- (1) Safeguard the connector assembly against flux penetration from its top side.
- (2) This product is designed on the assumption that they will not be washed after soldering.
- If youwash it, it may be cause deterioration of mechanically and electrically.
- If washing is necessary, pleasemake contact with us beforehand.
- 2. When soldering terminals, there is a danger that load placed on the terminals may cause rattle, deformayion or electrical degradation to occur depending on the conditions.

Caution is therefore required.

- 3. When soldering, do not use water soluble flux because this may corrode the product.
- 4.regarding the setting of reflow conditions, please confirm them with the actual mass production conditions.
- 5.As P.W.B. warping may alter characteristics, please take this into consideration when designing pattern and layout.
- 6.Please do not solder at the ejector pushing position.
- 7.To prevent contact disturbance by the sulfuration or oxidation of the conyact and terminal, and deterioration of solder ability by thin film on the terminal, please note following.
- Storage in the atmosphere of high temperature at 60 degrees or more, high humidity, corrosive gases such as sulfur or chlorinate gas, and excessive piling up of the carton boxes shall be avoided.
- Connectors shall be stored as the package not opened and in the normal temperature and normal humidity, and the connectors shall be used preferably within 3 months, at least within 6 months.
- When the connectors are stored after opening the package, the connectors shall be sealed with a polyethylene bag
 etc. and stored in dark and cool place, avoiding direct sunlight. Bag etc. and stored in dark and cool place, avoiding
 direct sunlight. The connectors shall be used as soon as possible.
- 8.Don't push or hold down the metal cover of the connector, otherwise there is a possibolity that the card would not be ejected or influences to other function.
- 9.Please attention following items to prevent connector from miss operation, such as bounding caused by ON/OFF switching and chattering by vibration.
- · Repeated reading/writing.
- Establish delay time-recommended 400msec min.
- · Establish CR accumulation circuit.
- 10. This product does not operate normally when the card which does not conform to the specification is used occasionally.